ISO9001 & ISO14001 & TS16949 **CHILISIN ELECTRONICS CORP.**

Halogen Free & RoHs Compliance

SPECIFICATION FOR APPROVAL

Customer :

Customer P/N:

Drawing No :

Quantity : **0** **Pcs.** **Date :** **2014/08/05**

Chilisin P/N : **HFY160808T-601Y-NP**

SPECIFICATION ACCEPTED BY:	
COMPONENT ENGINEER	
ELECTRICAL ENGINEER	
MECHANICAL ENGINEER	
APPROVED	
REJECTED	

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YG14800236

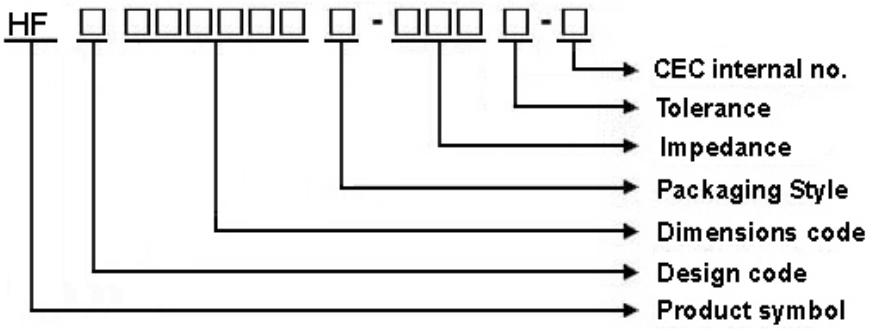
ISO9001 & ISO14001 & TS16949 CHILISIN ELECTRONICS CORP.

HFY160808T Series Specification

1 Scope:

This specification applies to MULTILAYER FERRITE CHIP BEADS

2 Part Numbering:



3 Rating:

Operating Temperature: －５５℃～１２５℃(Including self - temperature rise)

Storage Temperature: －５５℃～１２５℃(after PCB)
－５℃～４０℃,Humidity ４０%～７０%(before PCB)

4 Marking:

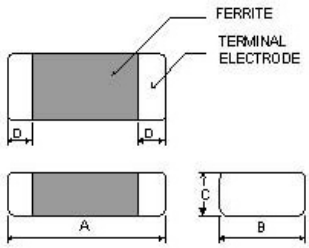
No Marking

5 Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35℃)	20±2℃
Humidity	Ordinary Humidity(25 to 85% RH)	60 to 70 % RH

HFY160808T Series Specification

6 Configuration and Dimensions:



Dimensions in mm

TYPE	HF160808
A	1.6±0.20
B	0.8±0.15
C	0.8±0.15
D	0.3±0.20

7 Electrical Characteristics:

Part No.	Impedance (Ω)±25%	Impedance (Ω)±40%	Test Freq. (MHZ)	RDC (Ω)Max.	Rated Current (mA)Max.
HFY160808T-331Y-NP	330	450	100/1000	0.21	500
HFY160808T-391Y-NP	390	520	100/1000	0.3	500
HFY160808T-471Y-NP	470	600	100/1000	0.21	500
HFY160808T-601Y-NP	600	700	100/1000	0.35	500
HFY160808T-102Y-NP	1000	1000	100/1000	0.5	450

NOTE: tolerance Y=±25%

1.Operating temperature range －５５℃～１２５℃(Including self - temperature rise)

2.Rate Current： Applied the current to coils, the temperature rise shall not be more than 30℃

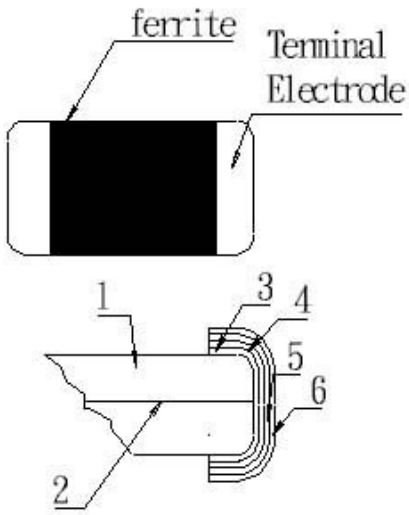
3.Impedance Test OSC @200mV

"-N" FOR COMPLETELY LEAD FREE TYPE(INCLUDING FERRITE BODY & SOLDER)

HFY160808T Series Specification

8 HFY160808T Series

8.1 Construction:



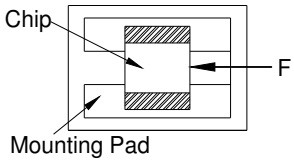
8.2 Material List:

NO	PART	MATERIAL
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite
2	Silver electrode	Ag
3	Silver electrode	Ag
4	Cu plating	Cu
5	Ni plating	Ni
6	Sn plating	Sn

HFY160808T Series Specification

9 Reliability Of Ferrite Multilayer Chip Bead

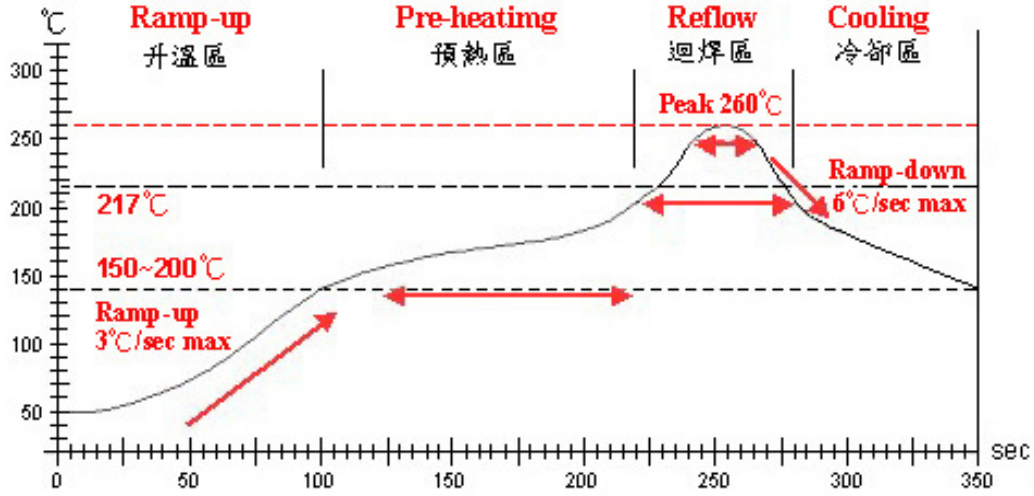
1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Impedance : within ±30% of initial value	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260±5℃ Immersion Time: 10±1sec
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5℃(Pb-Free) Immersion Time: 4±1sec
1-1-5	Terminal Strength Test	No split termination 	Test device shall be soldered on the substrate, then apply a force in the direction of the arrow. Force : 5N Keeping Time: 10±1sec

1-2.Environmental Performance

No	Item	Specification	Test Method
1-2-1	Temperature Cycle	Appearance: No damage Impedance: within±30% of initial value	One cycle: Step / Temperature (℃) / Time (min) 1 / -55±3 / 30 2 / 25±2 / 3 3 / 125±3 / 30 4 / 25±2 / 3 Total: 100cycles Measured after exposure in the room condition for 24hrs
1-2-2	Humidity Resistance		Temperature: 40±2℃ Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Resistance		Temperature: 125±3℃ / Relative Humidity: 0% Applied Current: Rated Current /Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Low Temperature Resistance		Temperature: -55±3℃ Relative Humidity: 0% / Time: 1000hrs Measured after exposure in the room condition for 24hrs

HFY160808T Series Specification



Reflow profile

Lead-Free(LF) 標準溫度分析範圍 Refer to J-STD-020C

管制項目 Item.	升溫區 Ramp-up	預熱區 Pre-heatimg	迴焊區 Reflow	Peak Temp	冷卻區 Cooling
溫度範圍 Temp.scope	R.T.~150℃	150℃~200℃	217℃	260±5℃	Peak Temp.~150℃
標準時間 Time spec.	—	60~180 sec	60~150 sec	20~40 sec	—
實際時間 Time result	—	75~100 sec	90~120 sec	20~35 sec	—

NOTE :

1. Re-flow possible times : within 2 times
2. Nitrogen adopted is recommended while in re-flow

HFY160808T Series Specification

10 Test Data for Pre-production Samples

Chilisin P/N: HFY160808T-601Y-NP

Measured Item		Z (Ω)	Z (Ω)	RDC (Ω)	A m/m	B m/m	C m/m	D m/m				
Spec	Customer	600±25%										
	Suggest		700±40%	0.35+0	1.6±0.2	0.8±0.15	0.8±0.15	0.3±0.20				
Test Freq.		200mV 100MHz	200mV 1000MHz									
1		532	758	0.226	1.63	0.89	0.9	0.35				
2		548	776	0.219	1.65	0.89	0.87	0.34				
3		568	807	0.234	1.66	0.87	0.88	0.38				
4		505	688	0.23	1.64	0.83	0.89	0.32				
5		569	809	0.234	1.64	0.85	0.85	0.34				
6		553	787	0.229	1.65	0.87	0.89	0.34				
7		553	785	0.234	1.65	0.89	0.84	0.35				
8		551	785	0.231	1.66	0.86	0.86	0.32				
9		519	736	0.231	1.63	0.85	0.85	0.34				
10		562	800	0.235	1.65	0.84	0.88	0.35				
11												
12												
13												
14												
15												
$\overline{X}$		546	773.1	0.2303	1.646	0.864	0.871	0.343				
R		64	121	0.016	0.03	0.06	0.06	0.06				
Customer												
Sample												

Test Instrument

HP4291A RF IMPEDANCE / MATERIAL ANALYZER FOR Z

CHEN HWA 502BC / HP4338B FOR RDC

Apperance and Dimensions:

SPEC : Refer to Item 6

Test Method : Visual Inspection and Measured with Slide Calipers.

Test Conditions:

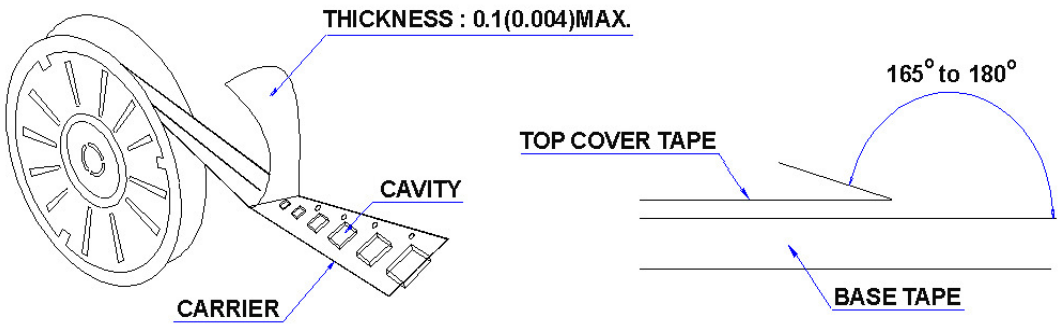
	Unless Otherwise Specified	In Case of Doubt
Temperature	Ordinary Temperature (15 to 35℃)	20 ± 2 ℃
Humidity	Ordinary Humidity (25 to 85 %RH)	60 to 70 %RH

HFY160808T Series Specification

11 Packaging:

11.1 Packaging -Cover Tape

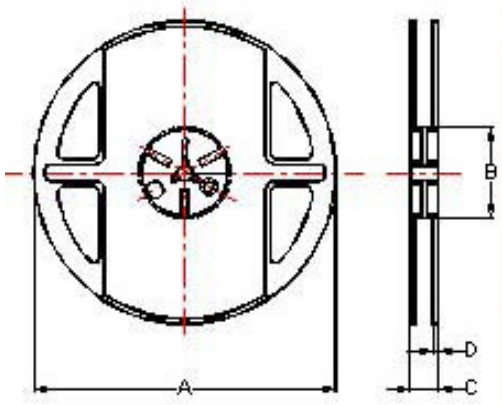
The force for tearing off cover tape is 10 to 100 grams in the arrow direction.



11.2 Packaging Quantity

TYPE	BULK	PCS/REEL
HF100505	✓	10000
HF160808	✓	4000

11.3 Reel Dimensions



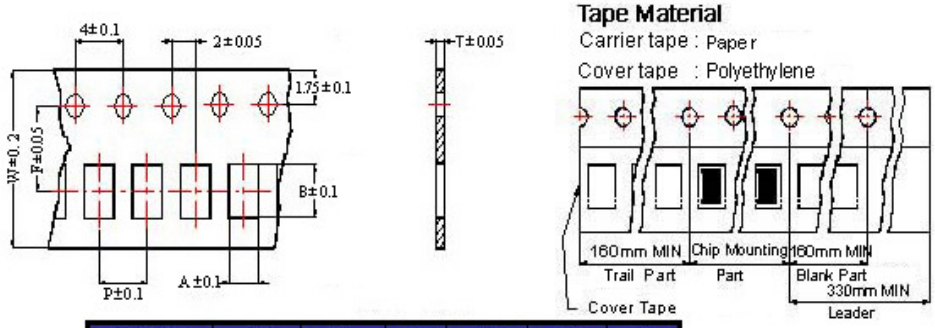
Dimensions in mm

TYPE	A	B	C	D
HF100505	178	60	12	1.5
HF160808	178	60	12	1.5

HFY160808T Series Specification

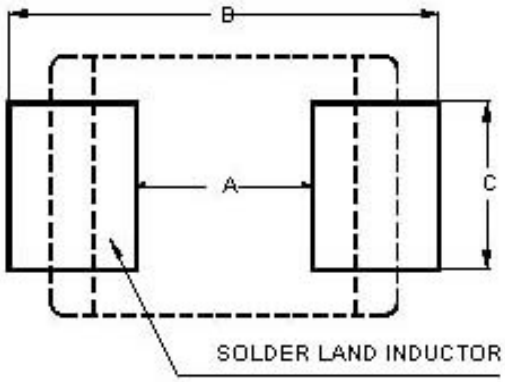
11 Packaging:

11.4 Tape Dimensions in mm



TYPE	A	B	T	W	P	F
HF100505	0.65	1.15	0.60	8	2	3.5
HF160808	1.05	1.85	0.95	8	4	3.5

12 Recommended Land Pattern:



Dimensions in mm

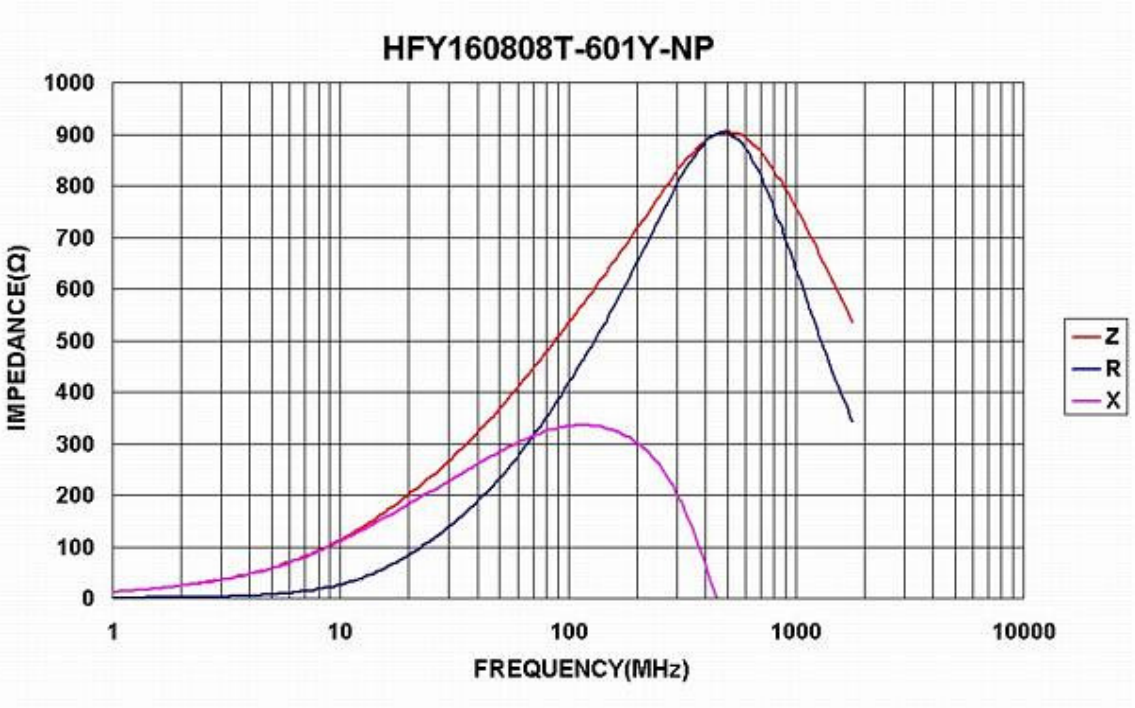
TYPE	A	B	C
HF100505	0.4	1.2 ~ 1.4	0.5
HF160808	0.7 ~ 0.8	1.8 ~ 2.0	0.6 ~ 0.8

13 Note:

1. Please make sure that your product has been evaluated and confirmed against your specifications when our product is mounted to your product.
2. Do not knock nor drop.
3. All the items and parameters in this product specification have been prescribed on the premise that our product is used for the purpose,under the condition and in the environment agreed upon between you and us. You are requested not to use our product deviating from such agreement.
4. Please keep the distance between transformer/coil and other components (refer to the standard IEC 950)

HFY160808T Series Specification

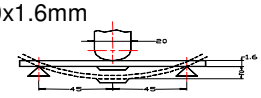
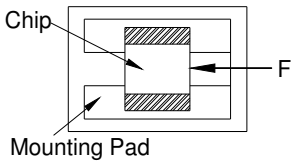
14 Graph:



A	**SB/PB/GB/NB/UPB/BAY/BAQ**	**Reliability Of Ferrite Multilayer Chip Bead**
B	**CLH**	**Reliability Of Ceramic Multilayer Chip Inductor For High Freq.**
C	**CL**	**Reliability Of Ferrite Multilayer Chip Inductor**
D	**SBH**	**Reliability Of Ceramicr Multilayer Chip Bead**
E	**NLC**	**Reliability Of Ferrite Wire Wound Chip Inductor For High Current**
F	**TFL**	**Reliability Of Thin Filmr Chip Inductor For High Freq.**
G	**Other**	**Reliability Of Ferrite Wire Wound Power Inductor**
H	**CMM**	**Common Mode Choke / RELIABILITY TEST**

A For SB/PB/GB/NB/UPB/BAY/BA 11 開始 每一頁 46

1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm 
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Impedance : within ±30% of initial value	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260±5℃ Immersion Time: 10±1sec
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5℃(Pb-Free) Immersion Time: 4±1sec
1-1-5	Terminal Strength Test	No split termination 	Test device shall be soldered on the substrate, then apply a force in the direction of the arrow. Force : 5N Keeping Time: 10±1sec

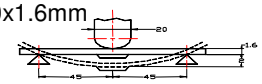
1-2.Environmental Performance

No	Item	Specification	Test Method
1-2-1	Temperature Cycle	Appearance: No damage Impedance: within±30% of initial value	One cycle: Step / Temperature (℃) / Time (min): 1 / -55±3 / 30 2 / 25±2 / 3 3 / 125±3 / 30 4 / 25±2 / 3 Total: 100cycles Measured after exposure in the room condition for 24hrs
1-2-2	Humidity Resistance		Temperature: 40±2℃ Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Resistance		Temperature: 125±3℃ / Relative Humidity: 0% Applied Current: Rated Current /Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Low Temperature Resistance		Temperature: -55±3℃ Relative Humidity: 0% / Time: 1000hrs

			Measured after exposure in the room condition for 24hrs

B For CLCN

1-1.Mechanical Performance

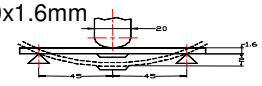
No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm 
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Inductance: within ±15% of initial value	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260±5℃ Immersion Time: 10±1sec
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5℃(Pb-Free) Immersion Time: 4±1sec

1-2.Environmental Performance

No	Item	Specification	Test Method
1-2-1	Temperature Cycle	Appearance: No damage Inductance:within±10% of initial value	One cycle: Step / Temperature (℃) / Time (min) 1 / -40±3 / 30 2 / 25±2 / 3 3 / 85±3 / 30 4 / 25±2 / 3 Total: 100cycles Measured after exposure in the room condition for 24hrs
1-2-2	Humidity Resistance		Temperature: 40±2℃ Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Resistance		Temperature: 85±3℃ Relative Humidity: 20% Applied Current: Rated Current / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Low Temperature Resistance		Temperature: -40±3℃ Relative Humidity: 0% / Time: 1000hrs Measured after exposure in the room condition for 24hrs

C For CLP

1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec 

			*For 100505, substrate dimension is 100x40x0.8mm
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Inductance: within ±15% of initial value	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260±5℃ Immersion Time: 10±1sec
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5℃(Pb-Free) Immersion Time: 4±1sec

1-2.Environmental Performance

No	Item	Specification	Test Method
1-2-1	Temperature Cycle	Appearance: No damage Inductance:within±10% of initial value	One cycle: Step / Temperature (℃) / Time (min) 1 / -40±3 / 30 2 / 25±2 / 3 3 / 105±3 / 30 4 / 25±2 / 3 Total: 100cycles Measured after exposure in the room condition for 24hrs
1-2-2	Humidity Resistance		Temperature: 40±2℃ Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Resistance		Temperature: 85±3℃ Relative Humidity: 20% Applied Current: Rated Current / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Low Temperature Resistance		Temperature: -40±3℃ Relative Humidity: 0% / Time: 1000hrs Measured after exposure in the room condition for 24hrs

D For CL

1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Inductance: within ±15% of	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260±5℃ Immersion Time: 10±1sec

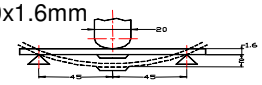
		initial value Q: within ±30% of initial value Inductance: within ±20% of initial value	
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5℃(Pb-Free) Immersion Time: 4±1sec

1-2.Environmental Performance

No	Item	Specification	Test Method
1-2-1	Temperature Cycle	Appearance: No damage Inductance:within±10% of initial value Q change:within±30% of initial value	One cycle: Step / Temperature (℃) / Time (min) 1 / -40±3 / 30 2 / 25±2 / 3 3 / 125±3 / 30 4 / 25±2 / 3 Total: 100cycles Measured after exposure in the room condition for 24hrs
1-2-2	Humidity Resistance		Temperature: 40±2℃ Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Resistance		Temperature: 85±3℃ Relative Humidity: 20% Applied Current: Rated Current / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Low Temperature Resistance		Temperature: -40±3℃ Relative Humidity: 0% / Time: 1000hrs Measured after exposure in the room condition for 24hrs

E For CL100505

1-1.Mechanical Performance

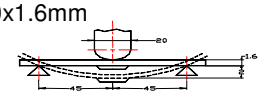
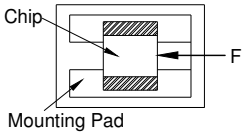
No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm 
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Inductance: within ±20% of initial value Q: within ±30% of initial value Inductance: within ±20% of initial value	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260±5℃ Immersion Time: 10±1sec
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5℃(Pb-Free) Immersion Time: 4±1sec

1-2.Environmental Performance

<table>
<tr><th>No</th><th>Item</th><th>Specification</th><th colspan="3">Test Method</th></tr>
<tr><td rowspan="7">1-2-1</td><td rowspan="7">Temperature Cycle</td><td rowspan="7">Appearance: No damage
Inductance:within±20% of initial value
Q change:within±30% of initial value</td><td colspan="3">One cycle:</td></tr>
<tr><td>Step</td><td>Temperature (℃)</td><td>Time (min)</td></tr>
<tr><td>1</td><td>-40±3</td><td>30</td></tr>
<tr><td>2</td><td>25±2</td><td>3</td></tr>
<tr><td>3</td><td>125±3</td><td>30</td></tr>
<tr><td>4</td><td>25±2</td><td>3</td></tr>
<tr><td colspan="3">Total: 100cycles
Measured after exposure in the room condition for 24hrs</td></tr>
<tr><td>1-2-2</td><td>Humidity Resistance</td><td colspan="4">Temperature: 40±2℃
Relative Humidity: 90 ~ 95% / Time: 1000hrs
Measured after exposure in the room condition for 24hrs</td></tr>
<tr><td>1-2-3</td><td>High Temperature Resistance</td><td colspan="4">Temperature: 85±3℃
Relative Humidity: 20%
Applied Current: Rated Current / Time: 1000hrs
Measured after exposure in the room condition for 24hrs</td></tr>
<tr><td>1-2-4</td><td>Low Temperature Resistance</td><td colspan="4">Temperature: -40±3℃
Relative Humidity: 0% / Time: 1000hrs
Measured after exposure in the room condition for 24hrs</td></tr>
</table>

F For BEAD0603

1-1.Mechanical Performance

<table>
<tr><th>No</th><th>Item</th><th>Specification</th><th>Test Method</th></tr>
<tr><td>1-1-1</td><td>Flexure Strength</td><td rowspan="2">The forces applied on the right conditions must not damage the terminal electrode and the ferrite</td><td>Test device shall be soldered on the substrate
Substrate Dimension: 100x40x1.6mm
Deflection: 2.0mm
Keeping Time: 30sec
 
*For 100505, substrate dimension is 100x40x0.8mm</td></tr>
<tr><td>1-1-2</td><td>Vibration</td><td>Test device shall be soldered on the substrate
Oscillation Frequency: 10 to 55 to 10Hz for 1min
Amplitude: 1.5mm
Time: 2hrs for each axis (X, Y & Z), total 6hrs</td></tr>
<tr><td>1-1-3</td><td>Resistance to Soldering Heat</td><td>Appearance: No damage
More than 75% of the terminal electrode should be covered with solder.
Impedance : within ±30% of initial value</td><td>Pre-heating: 150℃, 1min
Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
Solder Temperature: 260±5℃
Immersion Time: 10±1sec</td></tr>
<tr><td>1-1-4</td><td>Solder ability</td><td>The electrodes shall be at least 95% covered with new solder coating</td><td>Pre-heating: 150℃, 1min
Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free)
Solder Temperature: 245±5℃(Pb-Free)
Immersion Time: 4±1sec</td></tr>
<tr><td>1-1-5</td><td>Terminal Strength Test</td><td>No split termination
 
</td><td>Test device shall be soldered on the substrate, then apply a force in the direction of the arrow.
Force : 2N
Keeping Time: 10±1sec</td></tr>
</table>

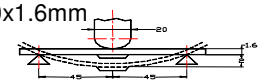
1-2.Environmental Performance

<table>
<tr><th>No</th><th>Item</th><th>Specification</th><th colspan="3">Test Method</th></tr>
<tr><td rowspan="6">1-2-1</td><td rowspan="6">Temperature Cycle</td><td rowspan="6">Appearance: No damage
Impedance: within±30% of initial value</td><td colspan="3">One cycle:</td></tr>
<tr><td>Step</td><td>Temperature (℃)</td><td>Time (min)</td></tr>
<tr><td>1</td><td>-55±3</td><td>30</td></tr>
<tr><td>2</td><td>25±2</td><td>3</td></tr>
<tr><td>3</td><td>125±3</td><td>30</td></tr>
<tr><td>4</td><td>25±2</td><td>3</td></tr>
</table>

			Total: 100cycles Measured after exposure in the room condition for 24hrs
1-2-2	Humidity Resistance		Temperature: 40±2℃ Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Resistance		Temperature: 125±3℃ / Relative Humidity: 0% Applied Current: Rated Current /Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Low Temperature Resistance		Temperature: -55±3℃ Relative Humidity: 0% / Time: 1000hrs Measured after exposure in the room condition for 24hrs

G For CP

1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm 
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage More than 75% of the terminal electrode should be covered with solder. Inductance: within ±20% of initial value	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260±5℃ Immersion Time: 10±1sec
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5℃(Pb-Free) Immersion Time: 4±1sec

1-2.Environmental Performance

No	Item	Specification	Test Method
1-2-1	Temperature Cycle	Appearance: No damage Inductance:within±20% of initial value	One cycle: Step / Temperature (℃) / Time (min) 1 / -40±3 / 30 2 / 25±2 / 3 3 / 105±3 / 30 4 / 25±2 / 3 Total: 100cycles Measured after exposure in the room condition for 24hrs
1-2-2	Humidity Resistance		Temperature: 40±2℃ Relative Humidity: 90 ~ 95% / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Resistance		Temperature: 85±3℃ Relative Humidity: 20% Applied Current: Rated Current / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Low Temperature Resistance		Temperature: -40±3℃ Relative Humidity: 0% / Time: 1000hrs Measured after exposure in the room condition for 24hrs

H For CLH

1-1.Mechanical Performance

No	Item	Specification	Test Method
1-1-1	Flexure Strength	The forces applied on the right conditions must not damage the terminal electrode and the ferrite	Test device shall be soldered on the substrate Substrate Dimension: 100x40x1.6mm Deflection: 2.0mm Keeping Time: 30sec *For 100505, substrate dimension is 100x40x0.8mm
1-1-2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency: 10 to 55 to 10Hz for 1min Amplitude: 1.5mm Time: 2hrs for each axis (X, Y & Z), total 6hrs
1-1-3	Resistance to Soldering Heat	Appearance: No damage	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 260±5℃ Immersion Time: 10±1sec
1-1-4	Solder ability	The electrodes shall be at least 95% covered with new solder coating	Pre-heating: 150℃, 1min Solder Composition: Sn/Ag3.0/Cu0.5(Pb-Free) Solder Temperature: 245±5℃(Pb-Free) Immersion Time: 4±1sec

1-2.Environmental Performance

No	Item	Specification	Test Method
1-2-1	Temperature Cycle	Appearance: No damage Inductance:within±10% of initial value Q change:within±30% of initial value	One cycle: Step / Temperature (℃) / Time (min) 1 / -55±3 / 30 2 / 25±2 / 3 3 / 125±3 / 30 4 / 25±2 / 3 Total: 100cycles Measured after exposure in the room condition for 24hrs
1-2-2	Humidity Resistance		Temperature: 40±2℃ Relative Humidity: 90 ~ 95% Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-3	High Temperature Resistance		Temperature: 125±3℃ Relative Humidity: 20% Applied Current: Rated Current / Time: 1000hrs Measured after exposure in the room condition for 24hrs
1-2-4	Low Temperature Resistance		Temperature: -55±3℃ Relative Humidity: 0% / Time: 1000hrs Measured after exposure in the room condition for 24hrs

DATA END

单击下面可查看定价，库存，交付和生命周期等信息

>>CHILISIN(奇力新)